

Groove Filling/Sealing

The Next Generation of Voidless Printing

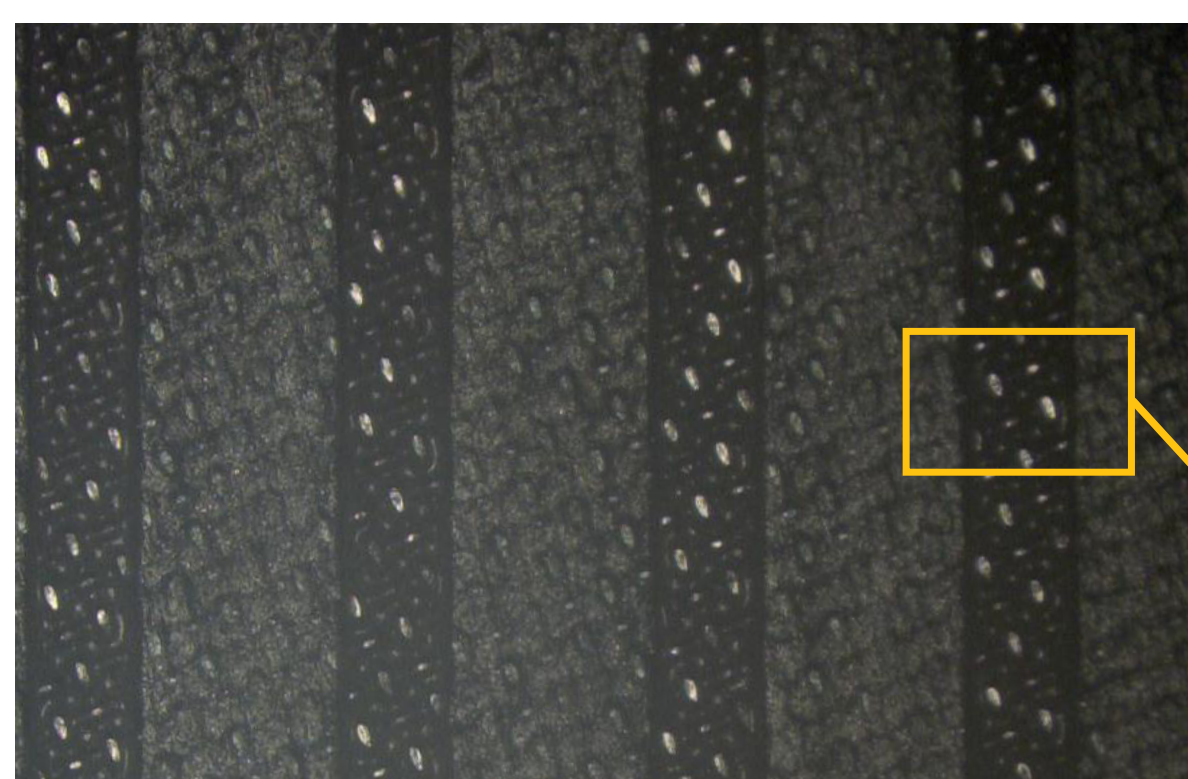
Equipment(SVM)

Groove-fill
Printing

Materials

Photograph

Vacuum Groove Printing



Atmospheric Printing

Insufficient
Groove Filling



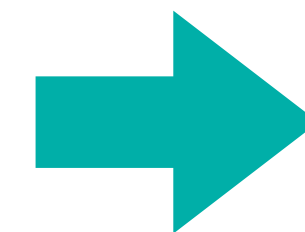
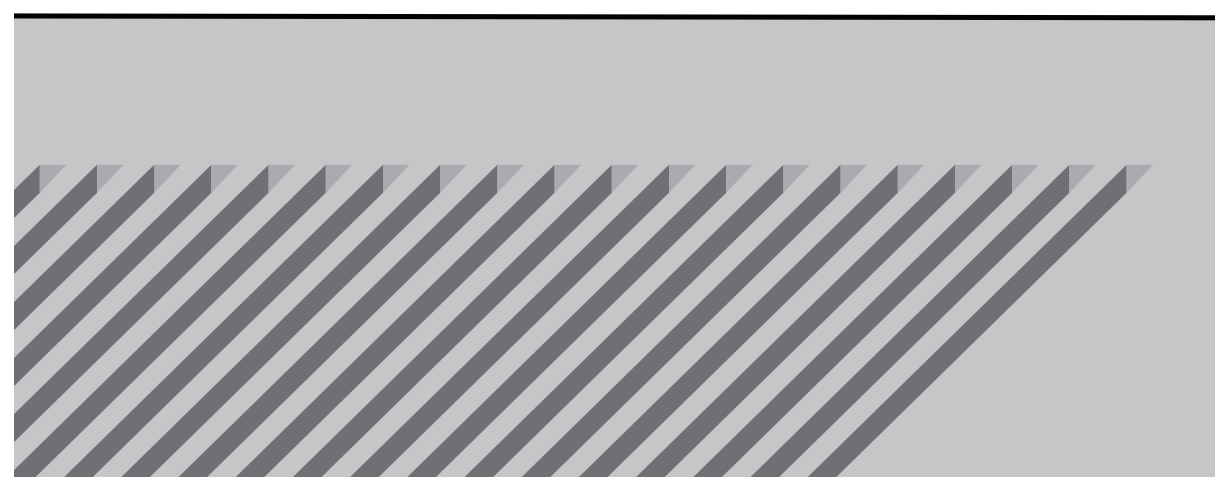
Vacuum Printing

Complete Groove Filling

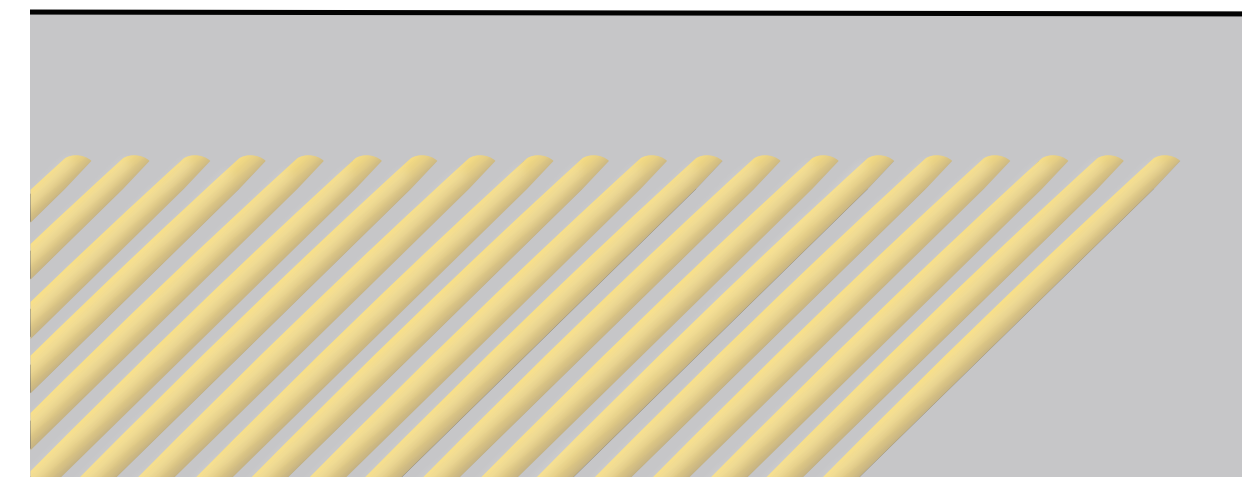


Groove Filling Proposal (Best Practice)

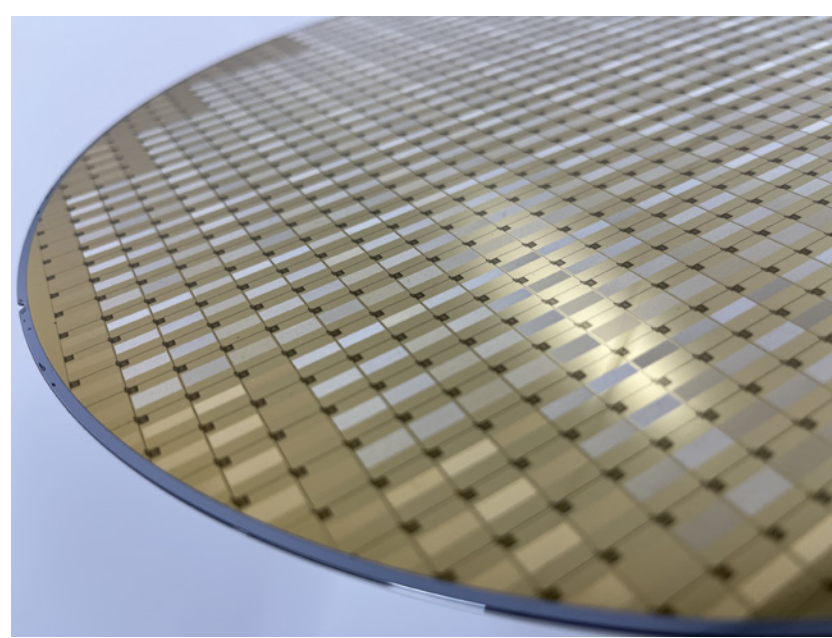
- Photoresist pattern processing is applied to the base material.



- Filling the inside of the processed groove with ink without voiding, and printing.

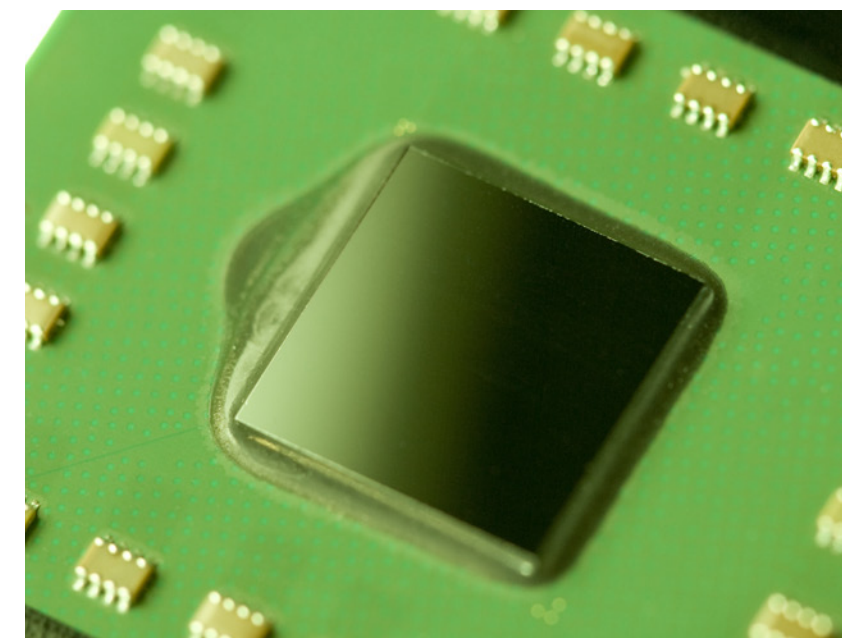
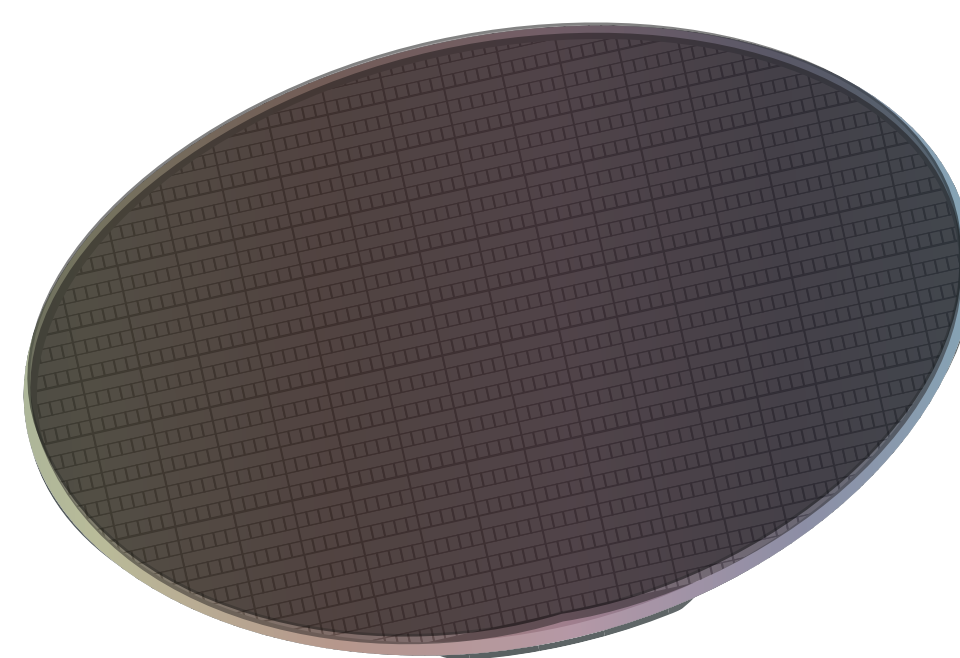


Vacuum Seal Printing



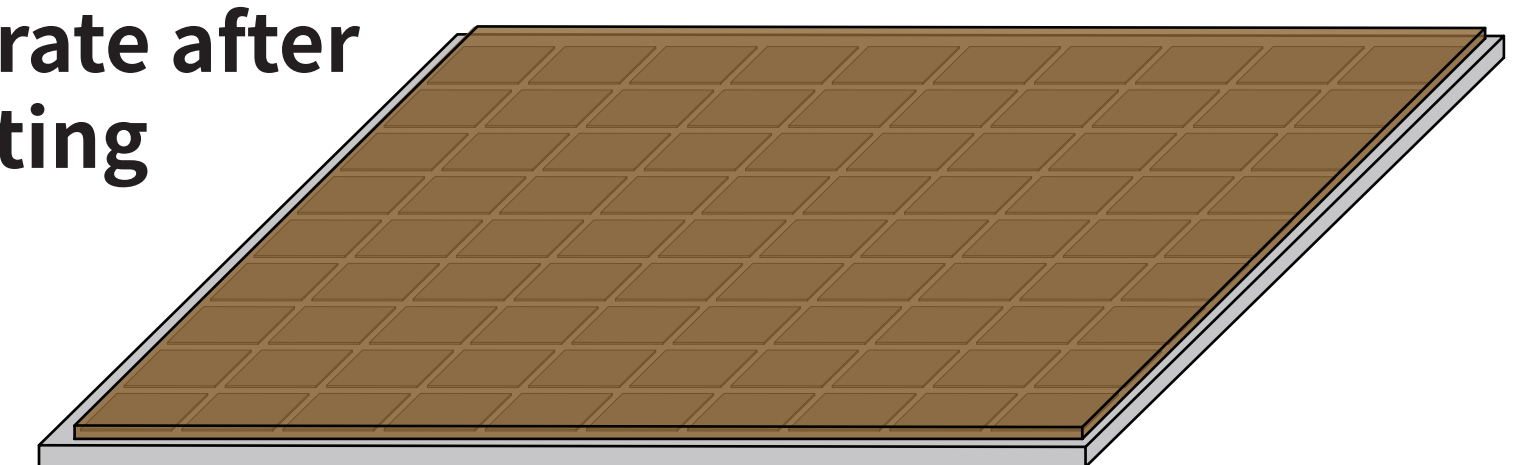
Wafer after Mounting

Sealing printing on the top surface of the mounting wafer.
Void-free sealing of the gap between the wafer and mounted components



Substrate after Mounting

Sealing printing on the top surface of the mounting package substrate
Void-free sealing of gap between the board and mounted components



Material Related

20mm thick cut squeegee rubber

- Urethane 20mm thick
- 60 degree angle polishing

